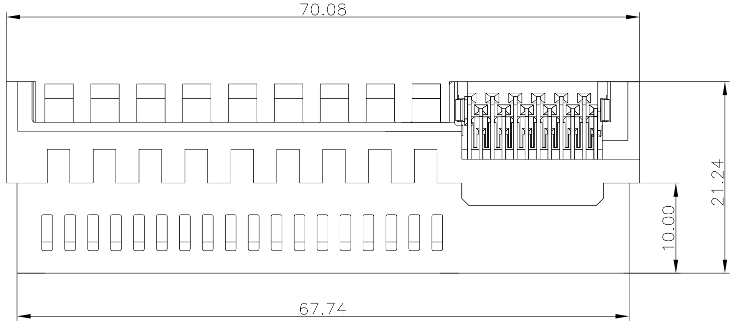
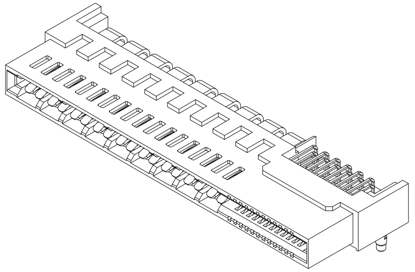
| REV. | SPECIFICATION | ECN NO. | APPD. |
|---|---|---|---|
| R2 |  | ECN230928 |  |





## Material and Plating:

Housing: LCP, UL94V-0 , Black.

Power Contacts: High Conductivity Copper,
Gold Plated or Au+Pd/Ni on Contact Area and 80μ" Min Tin Plated on Solder Tail over nickel 50μ" Min .

Signal Contacts: Phosphor Bronze,
Gold Plated or Au+Pd/Ni on Contact Area and 80μ" Min Tin Plated on Solder Tail over nickel 50μ" Min .

## Electrical Characteristics:

Current Rating: Signal Pin 1.5A.
Power Pin 12.5A(UL).

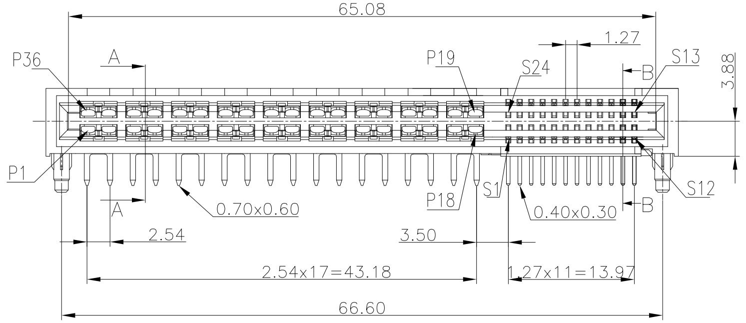
Dielectric Withstanding Voltage:
Signal Pin DC 500V For 1 Minute.
Power Pin DC 1000V For 1 Minute.

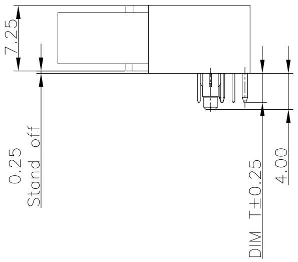
Contact Resistance: Signal Pin 25mΩ max.
Power Pin 0.6mΩ max.

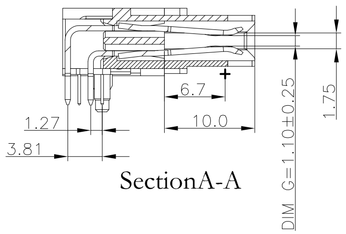
Insulator Resistance: Signal Pin 500MΩ min. at DC 500V
Power Pin 5000MΩ min. at DC 500V

Operating Temperature: -55°C~+105°C.

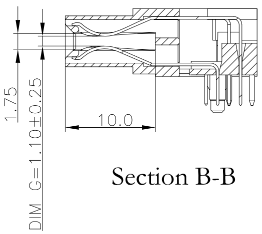
***Rohs Compliant**







SectionA-A



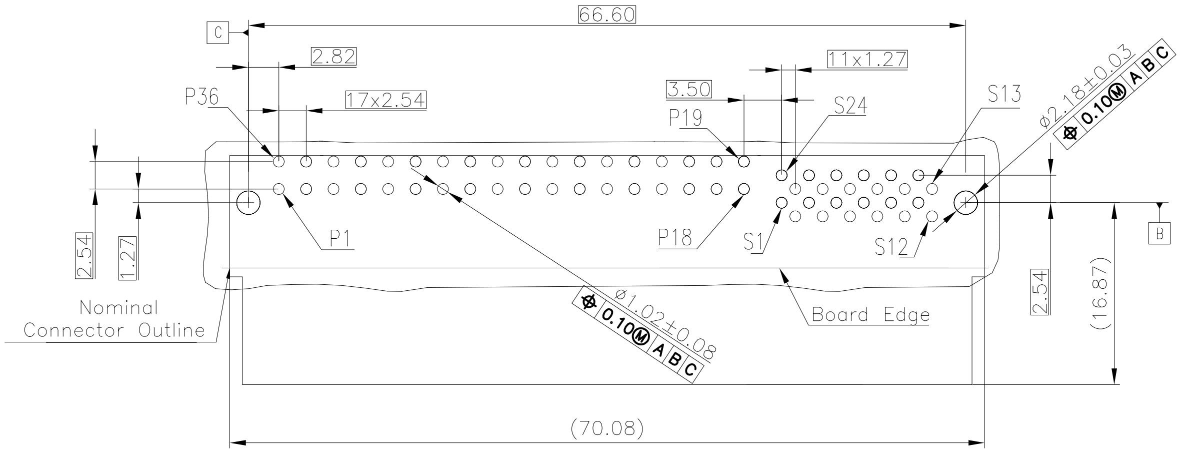
Section B-B

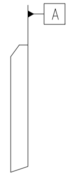
9302- 4 A17 S24 P 1 1 A CB30 D A

Series
4:Female Right-angle
A17:Power Assembly
S24:Signal Pin
N:W/O Post
P:With Post=4.00mm
1: DIM T=3.25mm
1: DIM G(GAP)1.10mm
A :Signal Pitch 1.27
B :Signal Pitch 2.54
CB30: Contact Au+Pd/Ni, Dip Tin 30u"
D:Dip Type
A: Tray Package

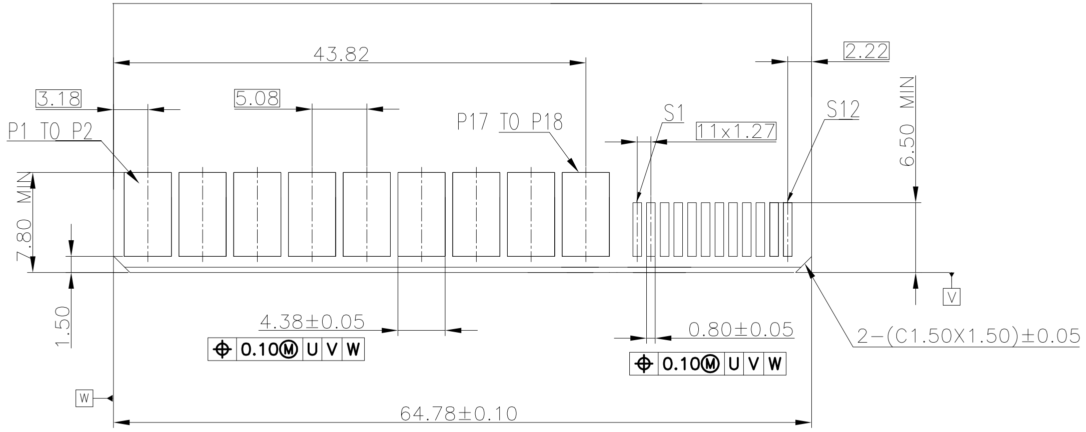
| Tolerances | Dwg No. | 9302-D0000-034 | Title: | OUPIIN<br>OUPIIN ELECTRONIC(KUNSHAN) CO., LTD. |
|---|---|---|---|---|
| X=0.5<br>.X=0.25<br>.XX=0.15 | Projection | ⌖ ◁ | 9302 Series<br>High Power And Signal<br>Edge Card Connector | P/N: 9302-4A17S24P11ACB30DA |
|  | Unit mm | Scale 1:1 |  | SHEET 1/2 |
|  | Drawn By | GYJ 09/19'23 | Ⓚ | Ver.No. R2 |

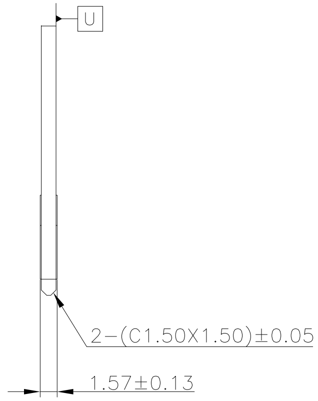
| REV. | SPECIFICATION | ECN NO. | APPD. |
|---|---|---|---|
| R2 | | ECN230928 | |





P.C. Board Layout
(Tolerance:±0.05)





Recommended Mating Board Foot Print
(Tolerance:±0.05)

| Tolerances | Dwg No. | 9302-D0000-034 | Title: | OUPIIN |
|---|---|---|---|---|
| X=0.5 | Projection | ⊕ ◁ | 9302 Series<br>High Power And Signal<br>Edge Card Connector | OUPIIN ELECTRONIC(KUNSHAN) CO., LTD. |
| .X=0.25 | Unit mm | Scale 1:1 | | P/N: 9302-4A17S24P11ACB30DA |
| .XX=0.15 | Drawn By | GYJ 09/19'23 | Ⓚ | SHEET 2/2 Ver.No. R2 |